Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S16	378	(substrate or board) with (component$1 or chip$1 or die$1 or IC$1) with (cavity or cavities or blind adj via$1) with (interconnect$4)	US-PGPUB; USPAT	OR	OFF	2005/02/06 14:29
S17	74	(substrate or board) with (component$1 or chip$1 or die$1 or IC$1) with (cavity or cavities or blind adj via$1) with (interconnect$4)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:28
S18	14	(substrate or board) with (component$1 or chip$1 or die$1 or IC$1) with (cavity or cavities or blind adj via$1) with (interconnect$4)	USOCR	OR	OFF	2005/02/06 14:07
S19	74	S17 not S16	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:07
S20	1397	(substrate or board) same (component$1 or chip$1 or die$1 or IC$1) same (cavity or cavities or blind adj via$1) same (interconnect$4)	US-PGPUB; USPAT	OR	OFF	2005/02/06 14:09
S21	176	(substrate or board) same (component$1 or chip$1 or die$1 or IC$1) same (cavity or cavities or blind adj via$1) same (interconnect$4)	USOCR	OR	OFF	2005/02/06 14:22
S22	185	(substrate or board) same (component$1 or chip$1 or die$1 or IC$1) same (cavity or cavities or blind adj via$1) same (interconnect$4)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:24
S23	868	S20 not (S16 or S14 or S12 or S10 or S7)	US-PGPUB; USPAT	OR	OFF	2005/02/06 14:10
S24	162	S21 not S18	USOCR	OR	OFF	2005/02/06 14:22
S25	111	S22 not S19	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:28
S26	19672	(substrate or board) with (component$1 or chip$1 or die$1 or IC$1) with (interconnect$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:49
S27	603	S26 and ((cavity or cavities or blind adj via$1) near6 (interconnect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:50

S28	166	S27 not (S25 or S23 or S19 or S18 or S16 or S14 or S12 or S10 or S7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:37
S29	1111	S26 and ((opening$1) near6 (interconnect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:37
S30	842	S29 not (S27 or S25 or S23 or S19 or S18 or S16 or S14 or S12 or S10 or S7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:50
S31	16643	(substrate or board) with (device$1) with (interconnect$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:49
S32	373	S31 and ((cavity or cavities or blind adj via$1) near6 (interconnect$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 14:50
S33	125	S32 not (S29 o r27 or S25 or S23 or S19 or S18 or S16 or S14 or S12 or S10 or S7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/06 15:02
S38	2974	(semiconductor adj chip) with (die)	US-PGPUB; USPAT	OR	OFF	2005/03/03 15:42
S39	2361	S38 and "257"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/03/03 15:42
S40	1920	(semiconductor adj chip) near3 (die)	US-PGPUB; USPAT	OR	OFF	2005/03/03 15:42